

Surface-mechanical and electrical property evaluation of nano-cone structured Cu–ZrO₂ composite coating

By

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ISMANAM-2019
July 8 – 12, 2019, Chennai

Introduction

Applications

Copper: wires, cables
Integrated Circuits
Printed circuit boards
Electrical busbars
Circuit inter connectors
Heat sinks
Heat exchangers, etc.

Advantages (Electrodeposition)

- Low cost and industrial applicability
- Simple operation
- High production rates
- Versatility
- Capability to handle complex geometry
- Precise control, near room temperature operation
- Reduction of waste

SURFACE
MODIFICATION OF

COPPER

(BY Cu-ZrO_2 COMPOSITE
COATING)

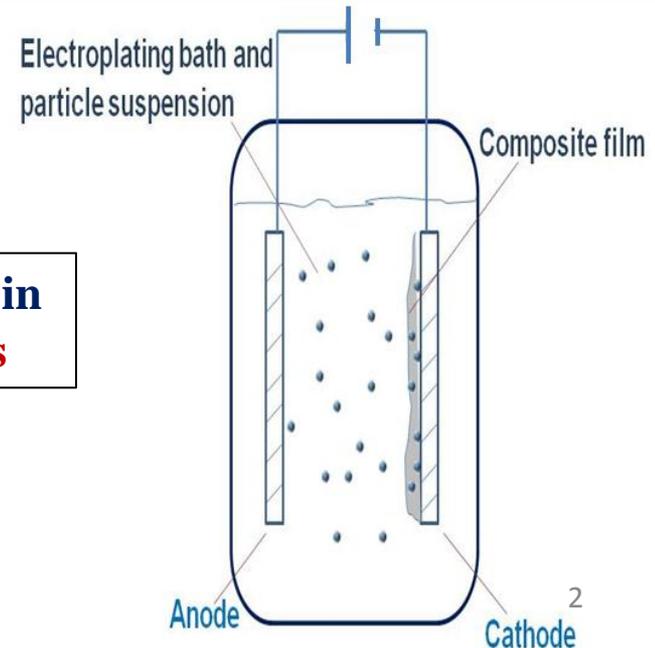
Without much
deterioration of
electrical
conductivity

Improvement in
Hardness, Wear

Possible application in
Electrical contacts

Properties

Higher electrical conductivity
Higher Thermal Conductivity
Corrosion resistance at
ambient temperature
Excellent workability
Abundantly available
Reproducible
Cheaper
Poor mechanical properties
Poor oxidation resistance



Experimental

Copper Sulfate Solution

Second phase particles (ZrO₂)

Suspension for Electro-codeposition (ECD)

Prepared Cu Substrate

Bath composition and deposition parameters:

Item	Details
Electrolyte	Copper Sulfate (CuSO ₄ ·5H ₂ O): 200 g/l, Sulfuric acid (H ₂ SO ₄): 50 g/l
pH	~2.17
Current density	8 A/dm ²
Temperature	Room temperature
Plating time	20 minutes
Dispersion	ZrO ₂ : 10 g/l
Surfactant	Cetyl trimethylammonium bromide (CTAB): 0.1, 0.5 and 1 g/l
Deposition mode	Pulsed electrodeposition [pulse frequency: 5 kHz and duty cycle (pulse on time):30%]

ECD Process (pulsed)

Characterizations

Phase Analysis (XRD)

Composition & Microstructure (EDS, SEM, FESEM)

Mechanical (Hardness, Wear)

Electrical conductivity

Powder characterizations

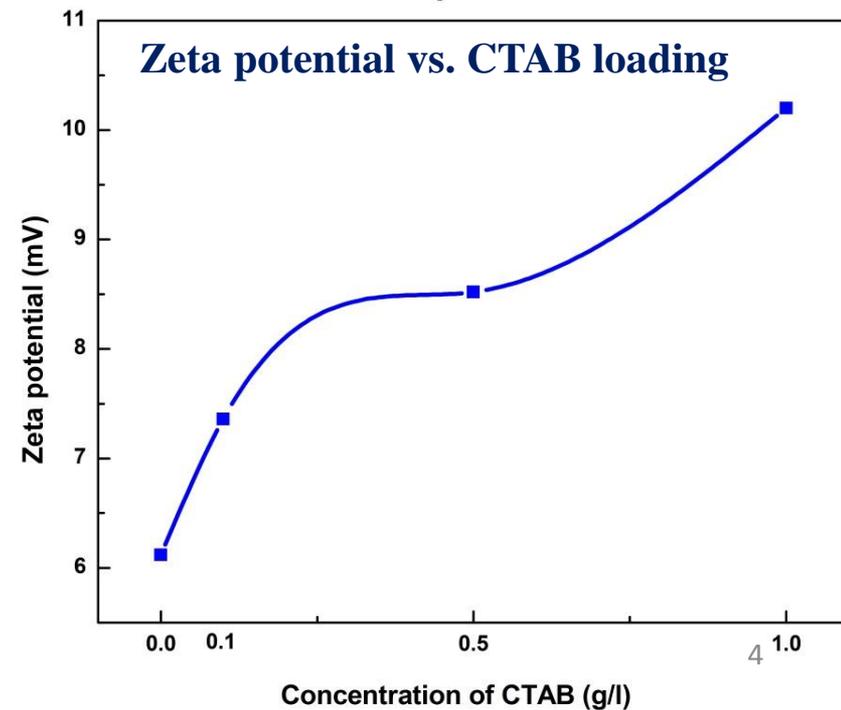
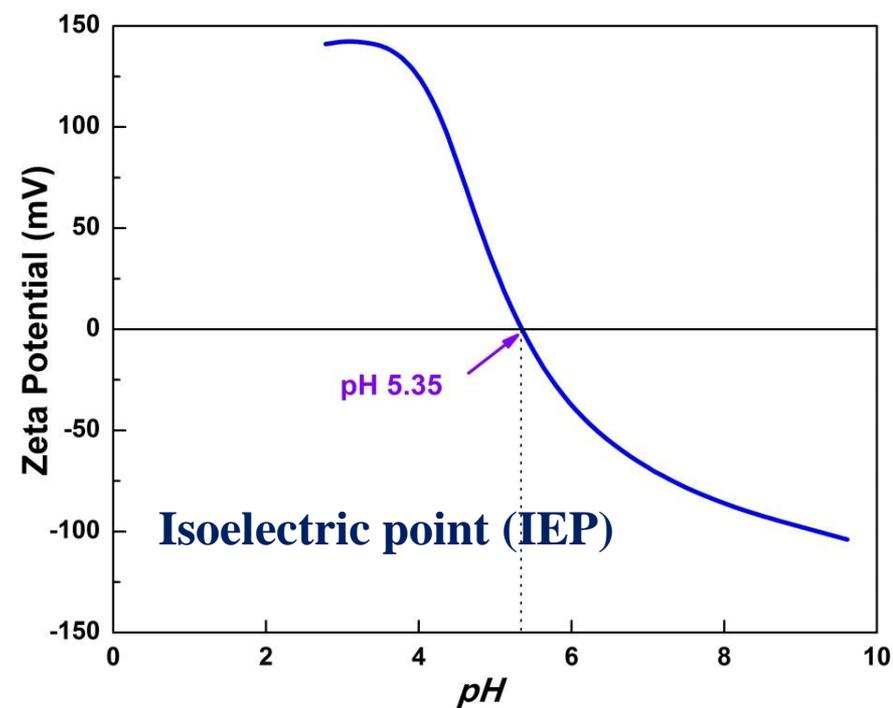
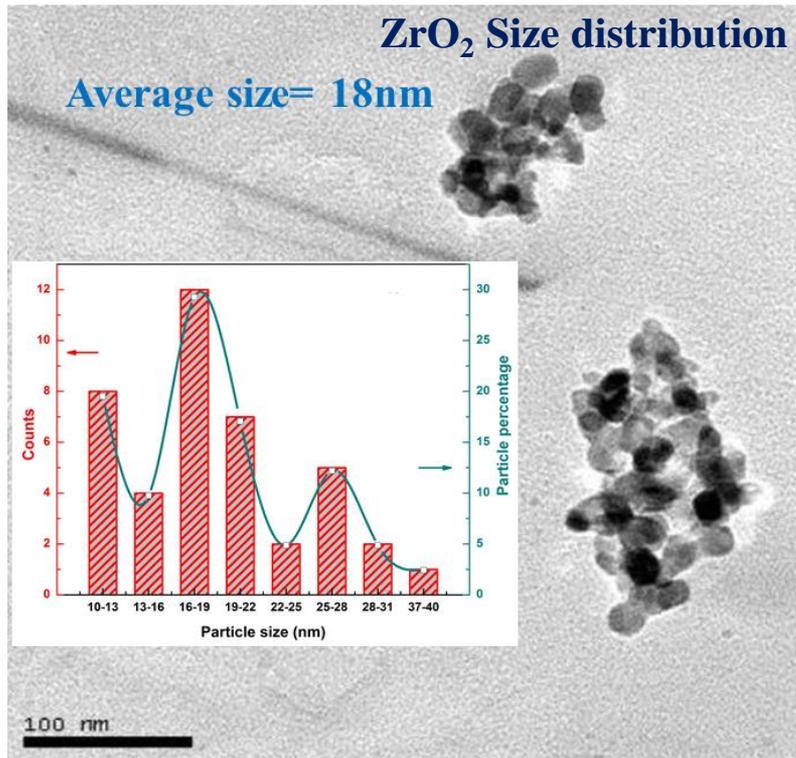
IEP = 5.35 pH

The Electrolyte pH < IEP



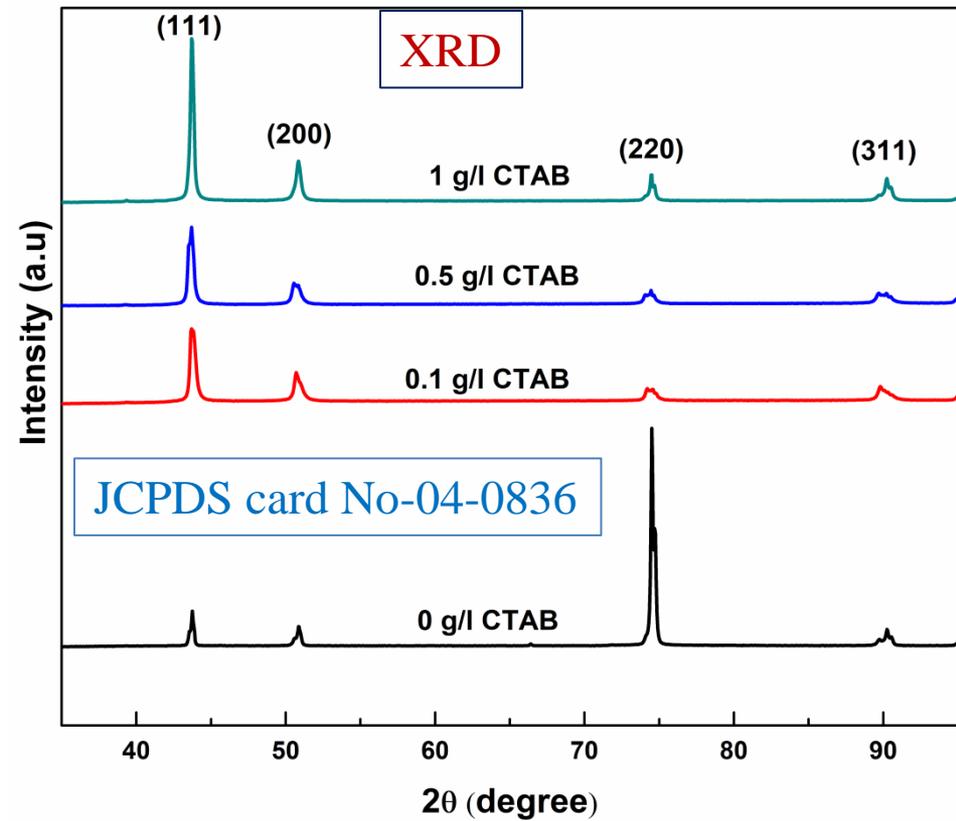
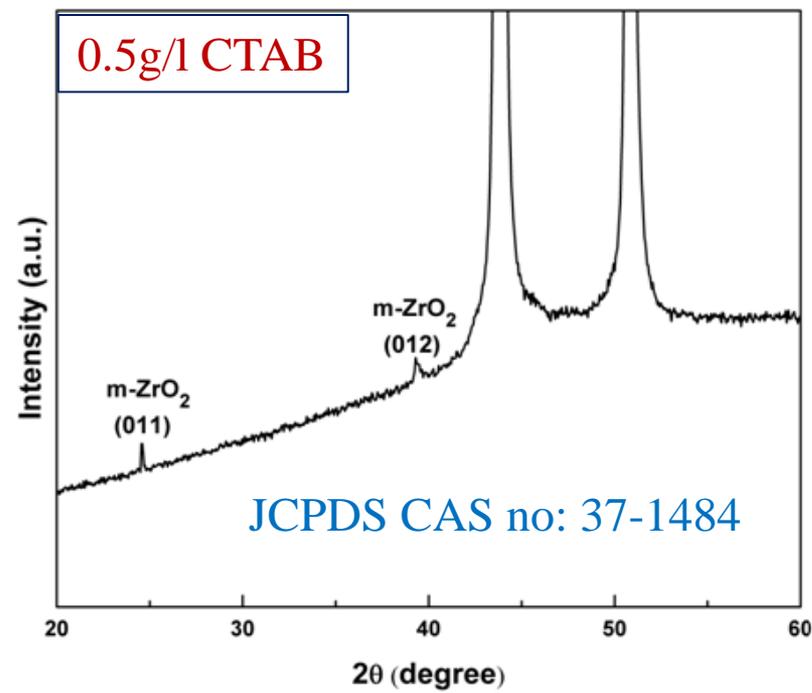
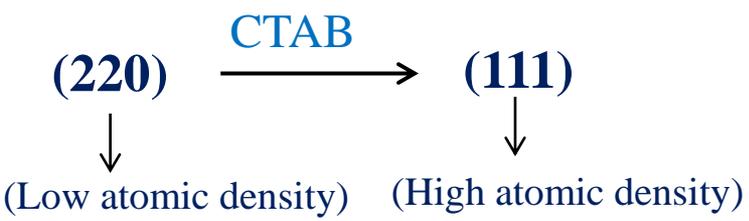
- To avoid possible agglomerations of ZrO_2
- Uniform codeposition of ZrO_2 particles

Size ranges from 13–37 nm



XRD analysis:

$$RTC_{(hkl)} = \frac{I_{(hkl)} / I_{0(hkl)}}{\sum (I_{(hkl)} / I_{0(hkl)})} \times 100\%$$



Relative Texture Coefficients:

Sample Details	RTC _(hkl) %			
	(111)	(200)	(220)	(311)
Without CTAB	03	04	85	08
0.1g/l (CTAB)	28	24	22	26
0.5g/l (CTAB)	45	21	20	14
1.0g/l (CTAB)	34	19	30	17

Microstructures:

Coarse

0.1g/L ↓

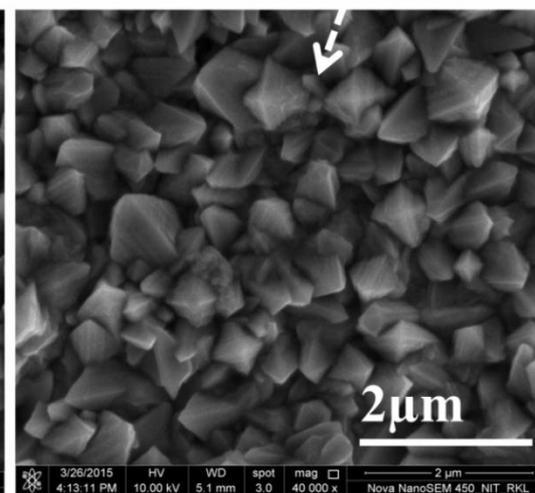
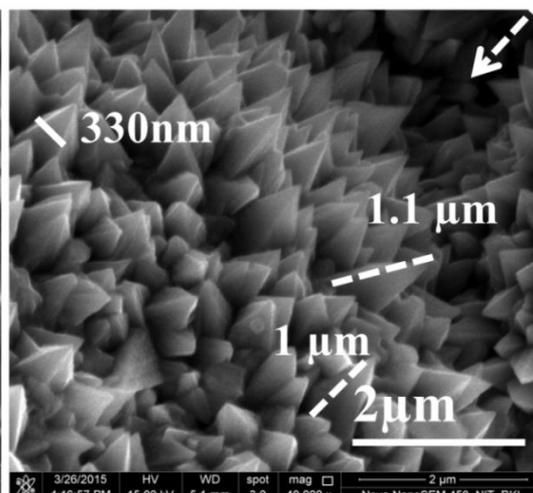
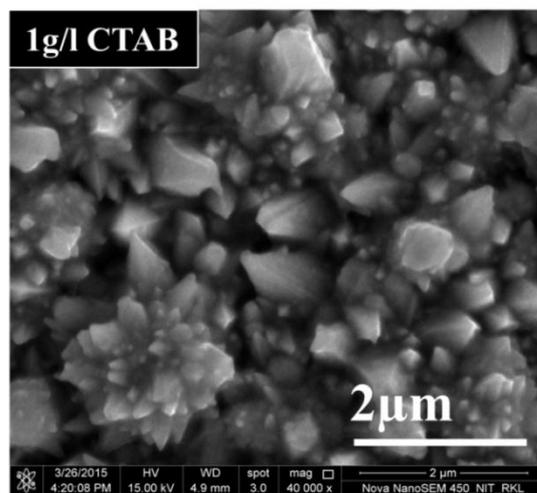
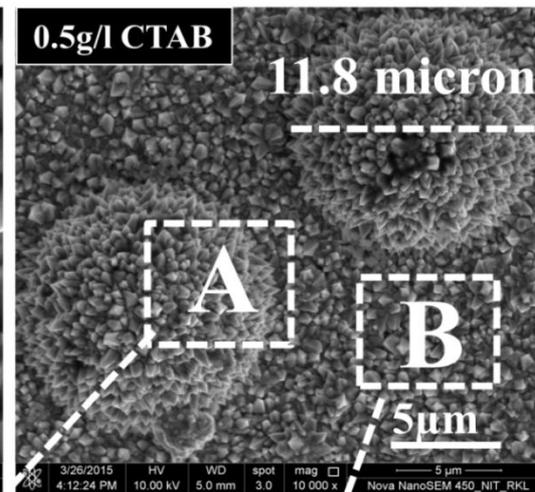
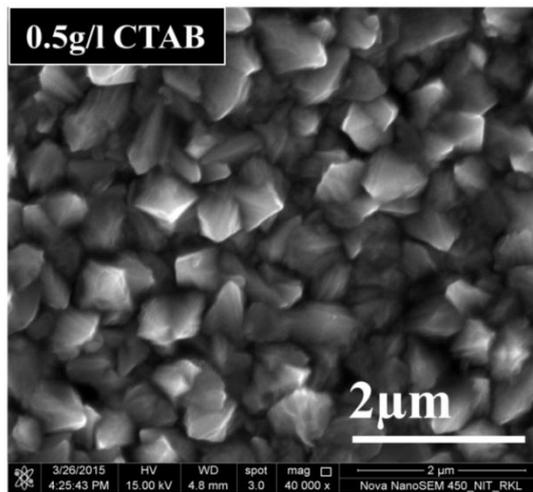
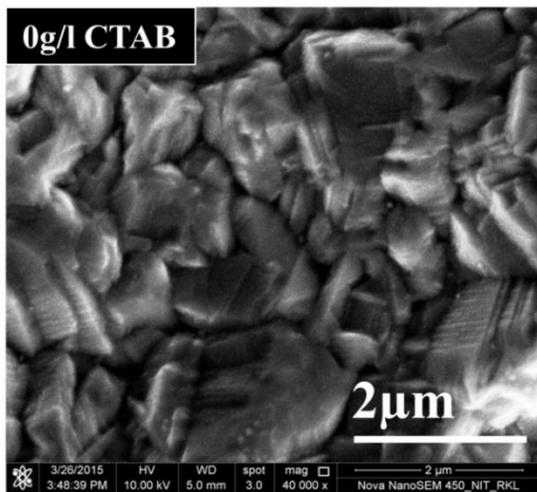
Finer nano-cone

0.5g/L ↓

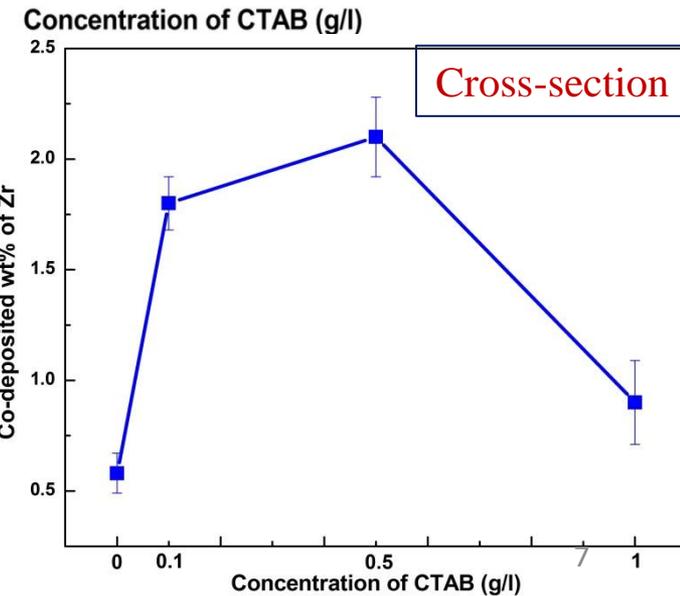
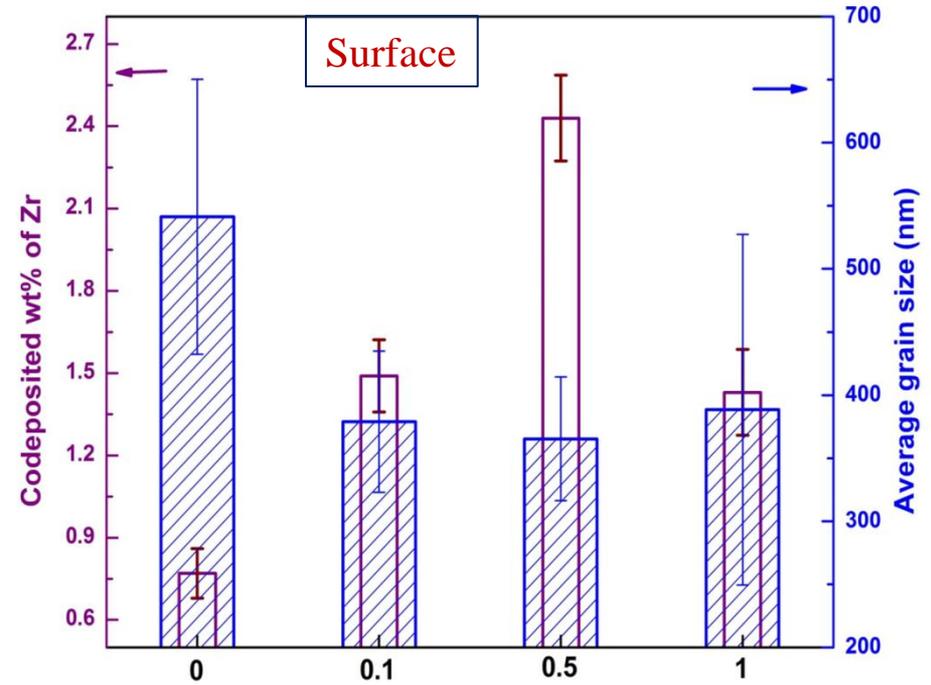
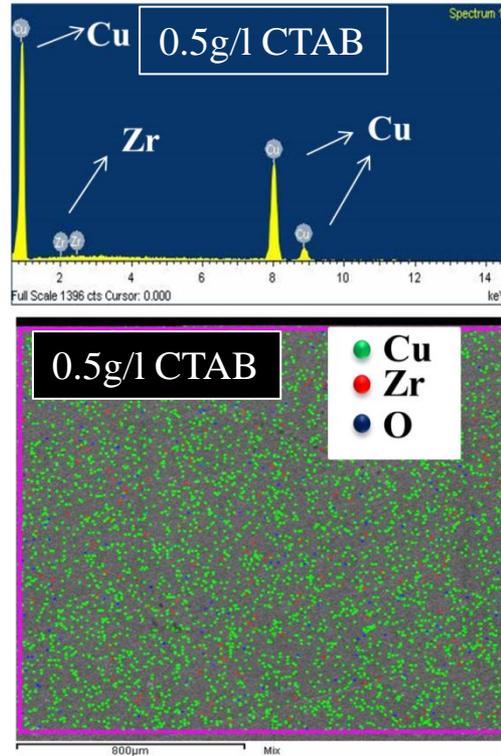
Duplex hemispherical with hierarchical nano-cone

1g/L ↓

Dual structured flowery appearance with hierarchical nano-cone



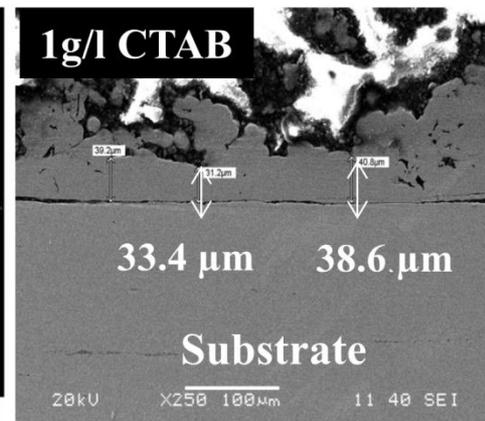
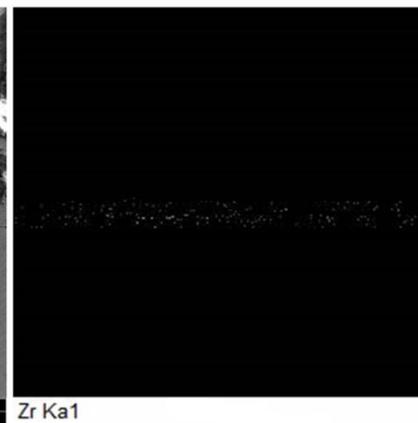
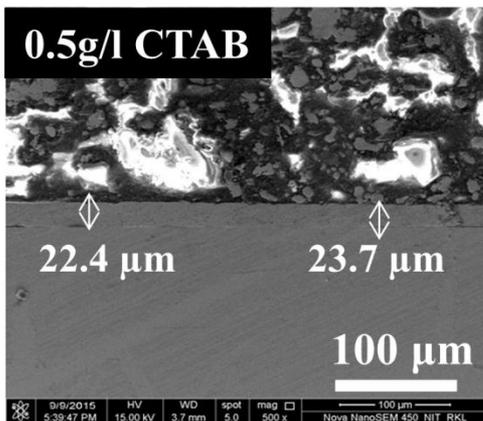
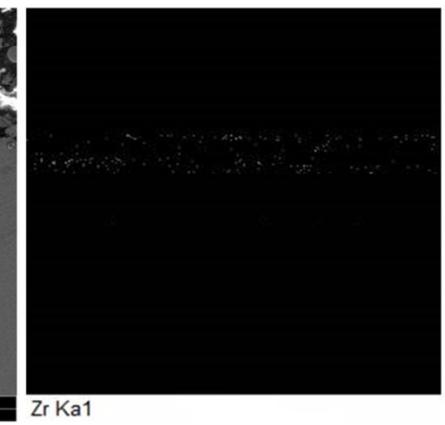
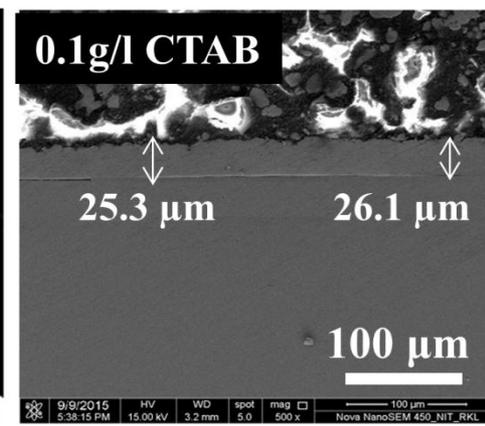
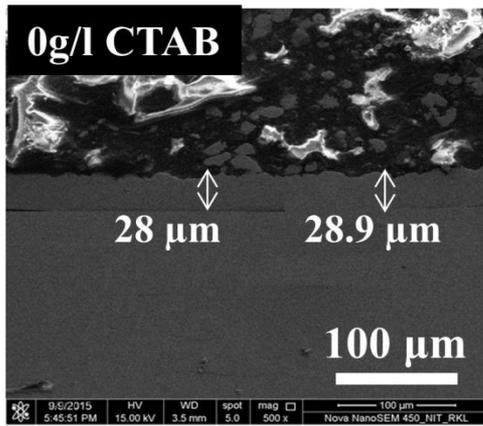
Compositional analysis:



- Confirmation of presence and uniform distribution of Zr along with O in Cu matrix
- CTAB addition up to 0.5g/l facilitates ZrO_2 codeposition.

Coating thickness:

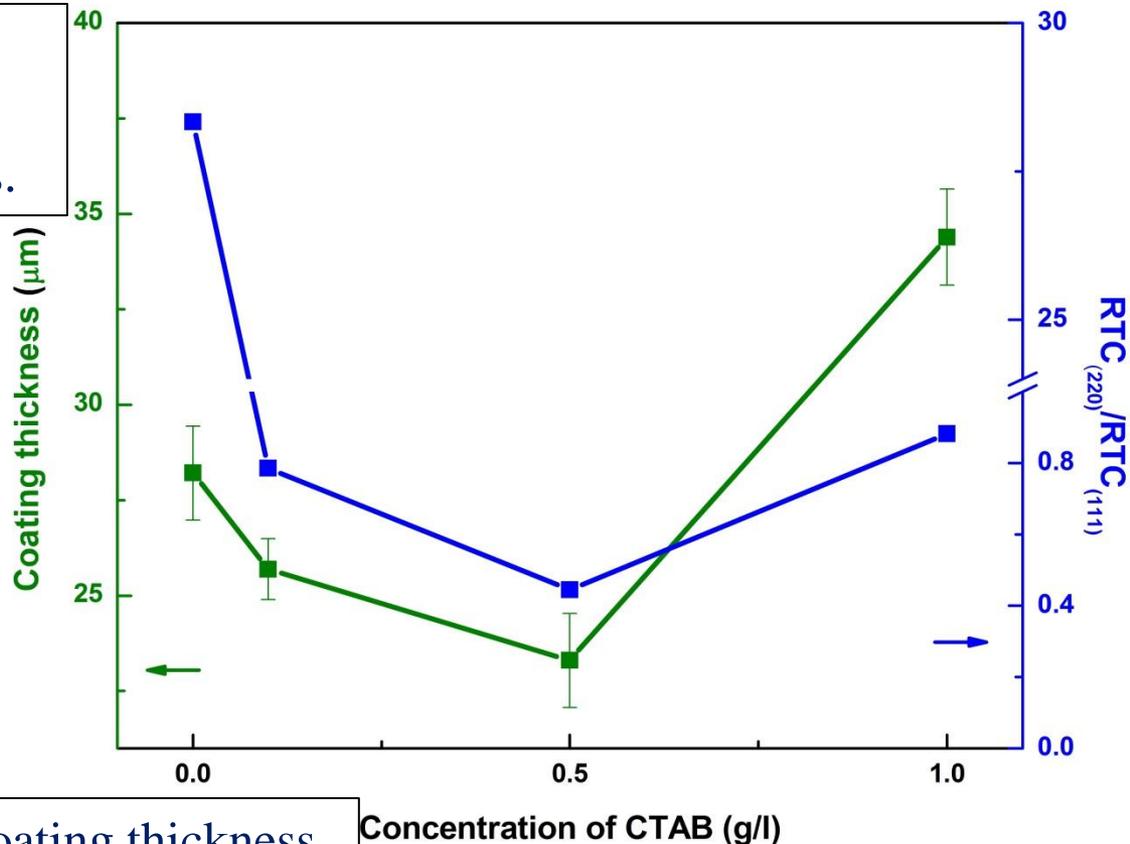
- Zr mapping of cross-sections also confirm the ZrO_2 codeposition.
- CTAB concentration (up to 0.5g/l) is proportional to $\frac{1}{\text{Film thickness}}$
- Coating thickness \sim crystallographic orientation \sim nucleation growth \sim ZeO_2 content



CTAB addition in electrolyte up to 0.5g/l may lower the Cu deposition rate and decrease the film thickness.

(111) Orientation \uparrow

Coating thickness \downarrow



$RTC_{(220)}/RTC_{(111)}$ is proportional to coating thickness

Concentration of CTAB (g/l)

Decrease of film thickness.

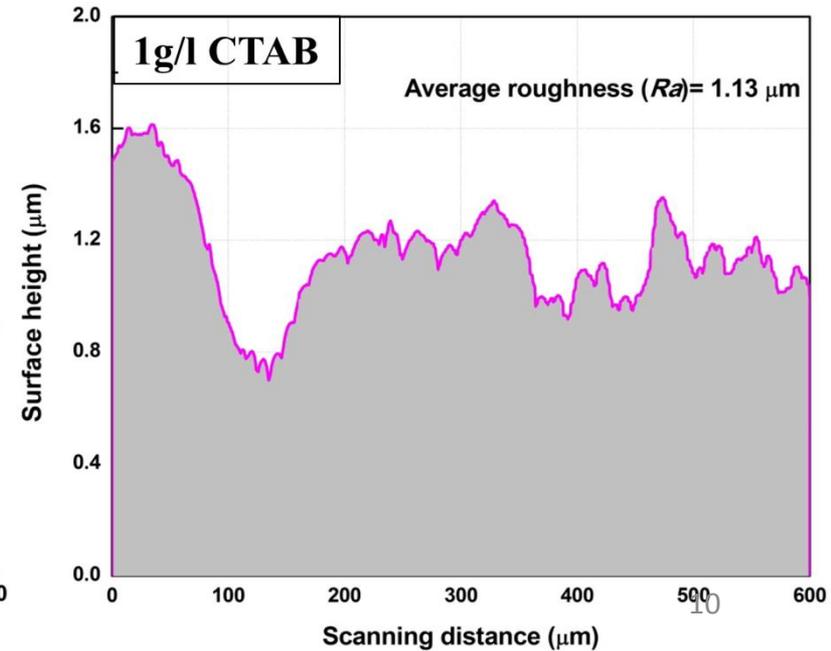
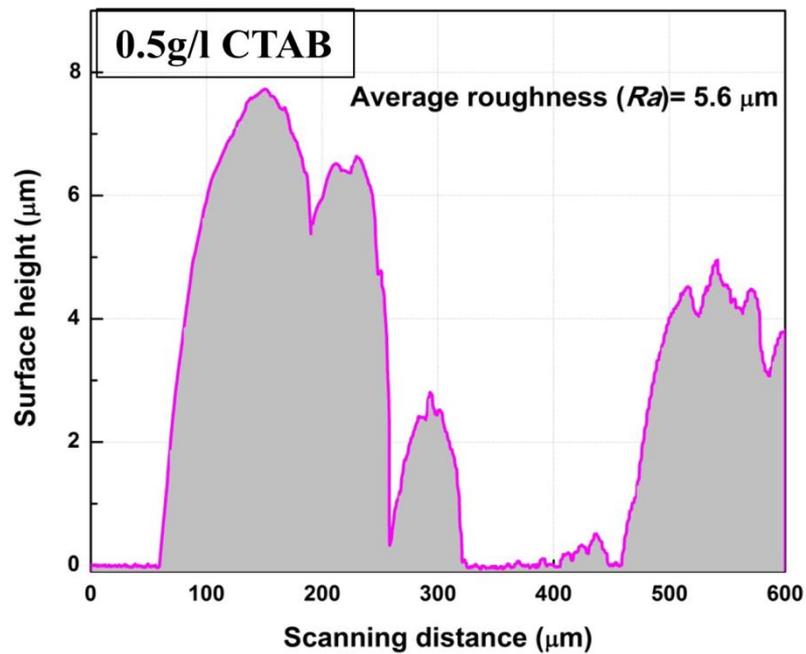
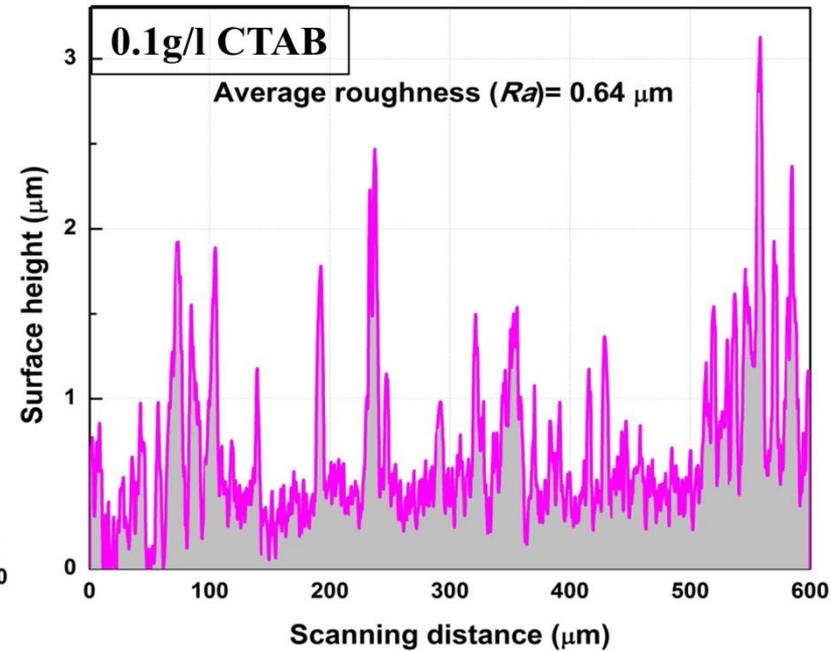
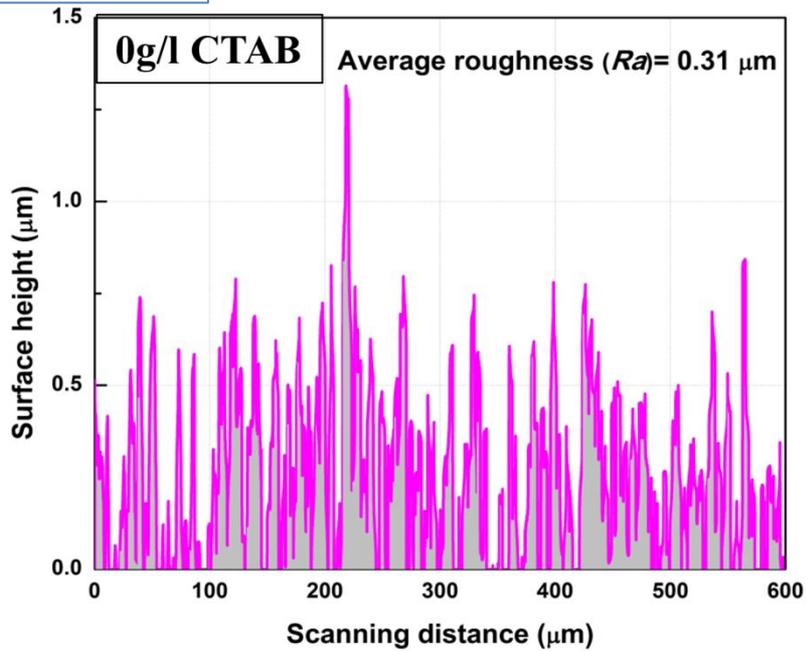


Decreasing amount of strain energy may be accommodated.



The (111) texture is favoured (Because (111) planes accommodate lesser strains than (220) planes).

Surface roughness:



Hardness:

Dual hardness

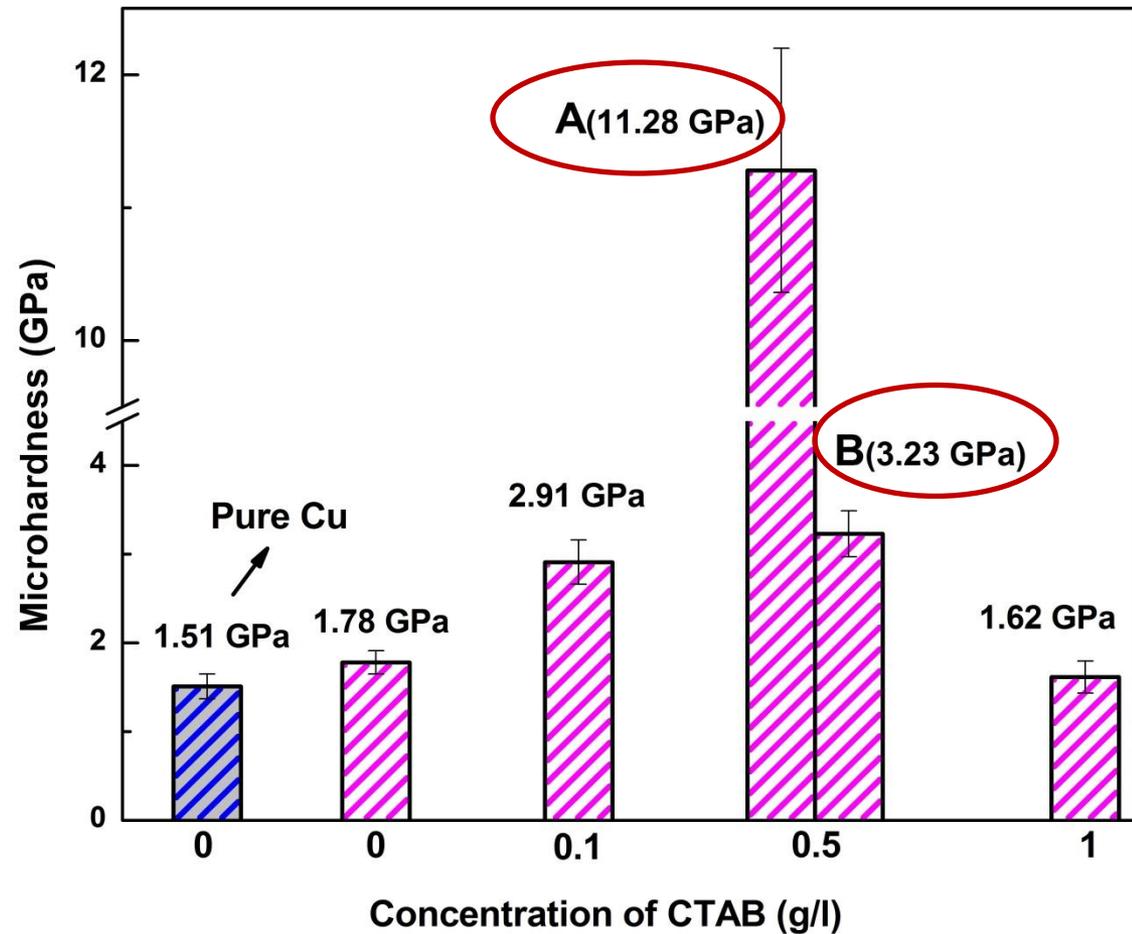


0.5g/l CTAB added coating

Higher hardness of Cu-ZrO₂ coating



- Codeposition of ZrO₂ particle
- Preferred (111) orientation
- Conical coating structure



Lowest hardness of 1.0 g/l CTAB coating among all composite coatings



- Coarser matrix compared to 0.1 and 0.5 g/l CTAB added coating.
- Smaller value of $RTC_{(111)}$ and lower value of ZrO₂ content in the coating.

Wear analysis:

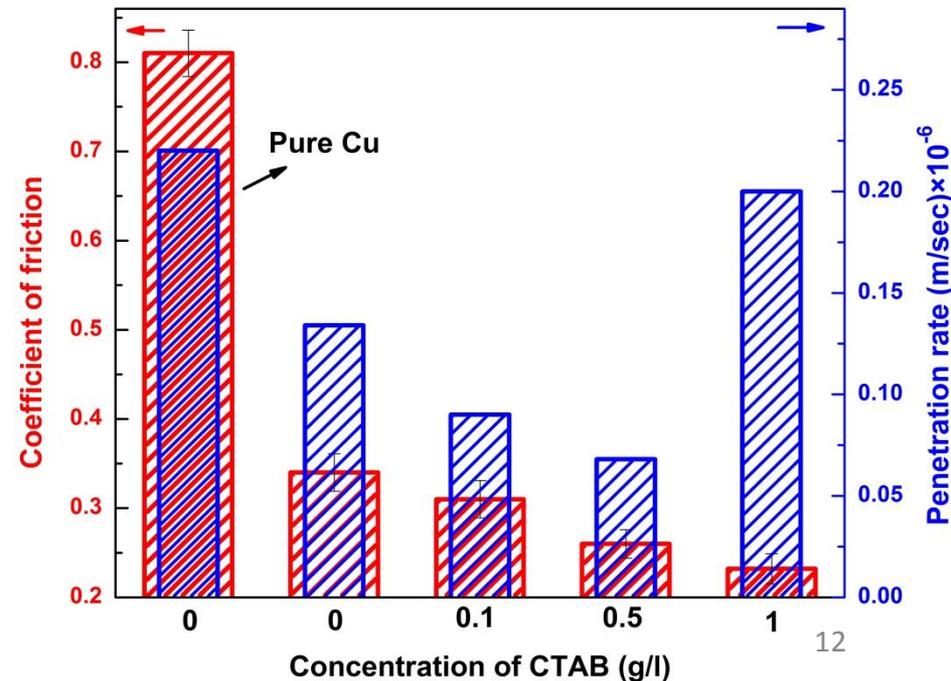
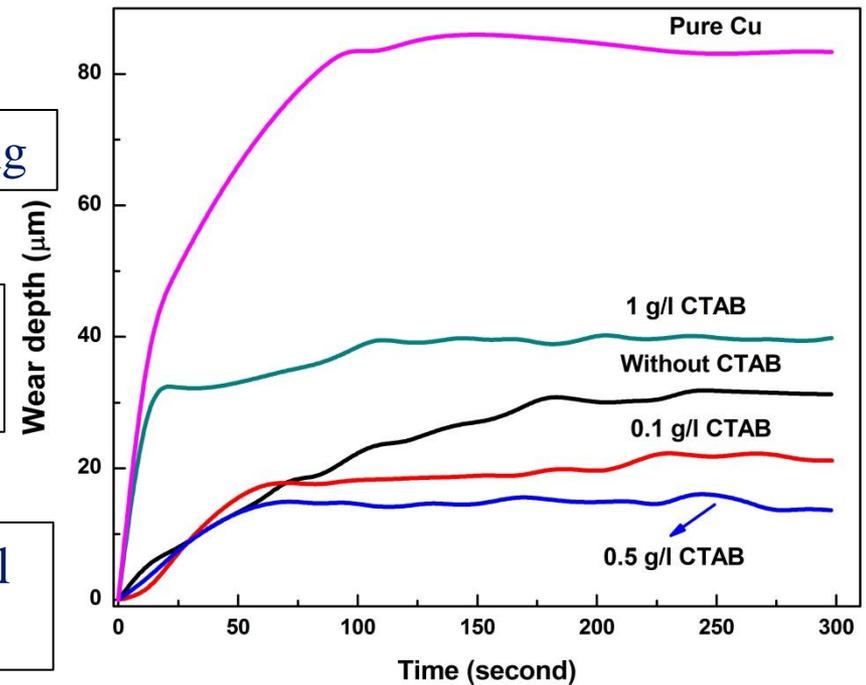
Lowest wear depth → 0.5g/l CTAB added coating

Wear depth result is similar to hardness trend.
Penetration rate also depict similar trend.

- Coefficient of friction (COF) is proportional to CTAB loading.

Lowest COF of 1g/l CTAB added coating
(in spite of lower wear resistance and hardness)

Due to less contact between indenter and coating surface



Electrical conductivity:

Without CTAB coating = 50.2% of IACS

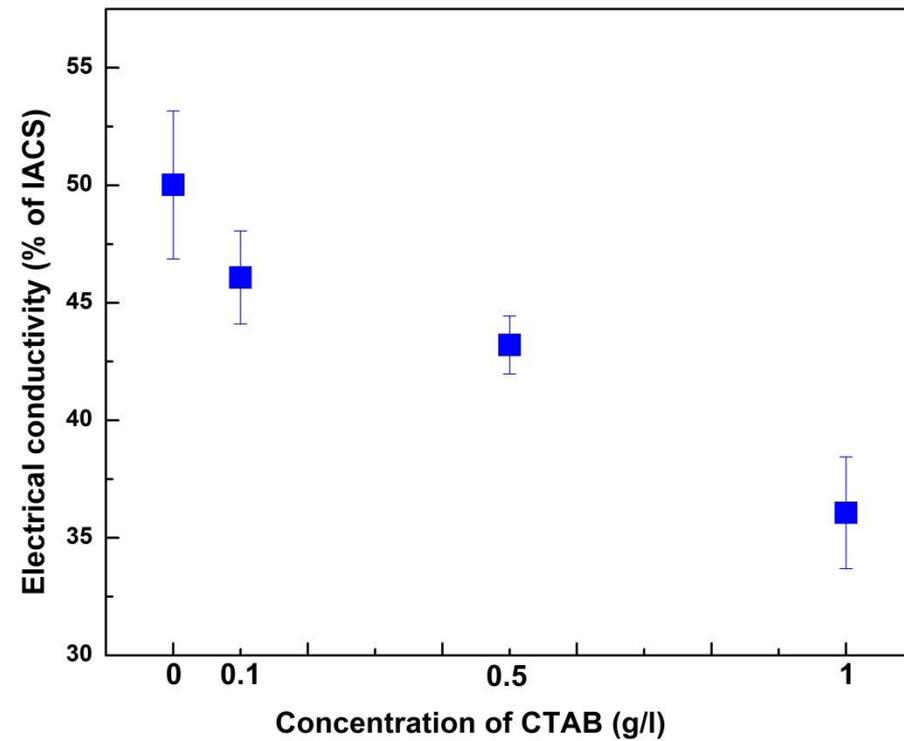
CTAB added coating = 36.3-46% of IACS

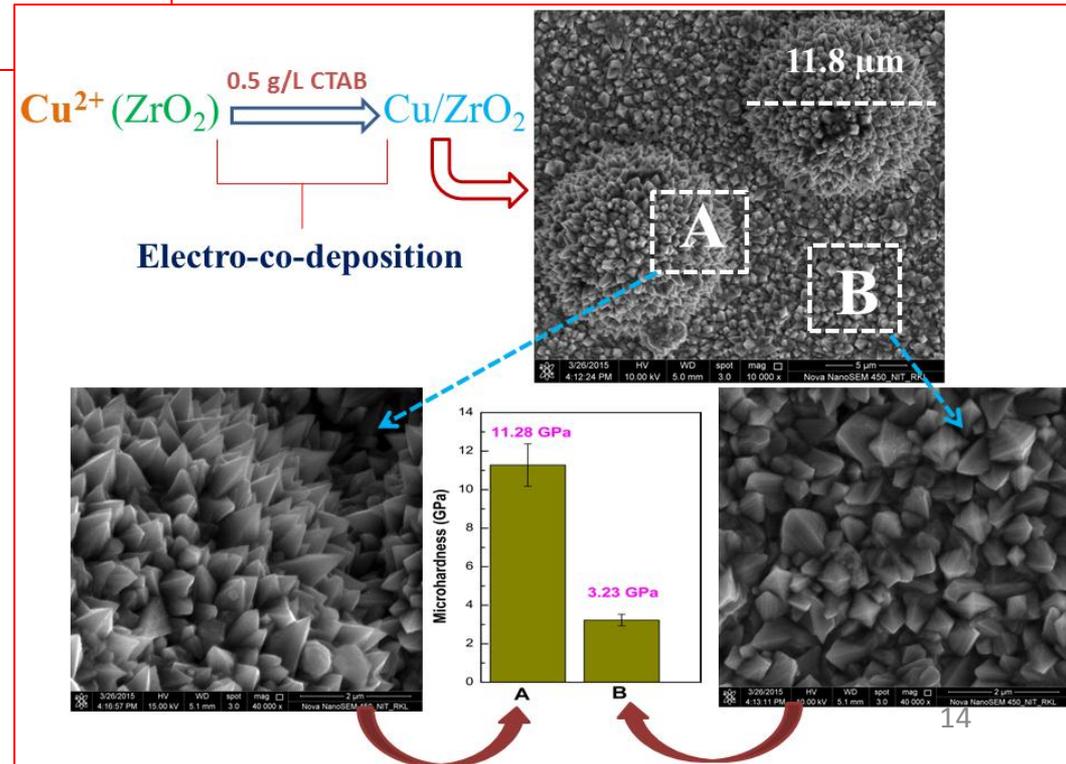
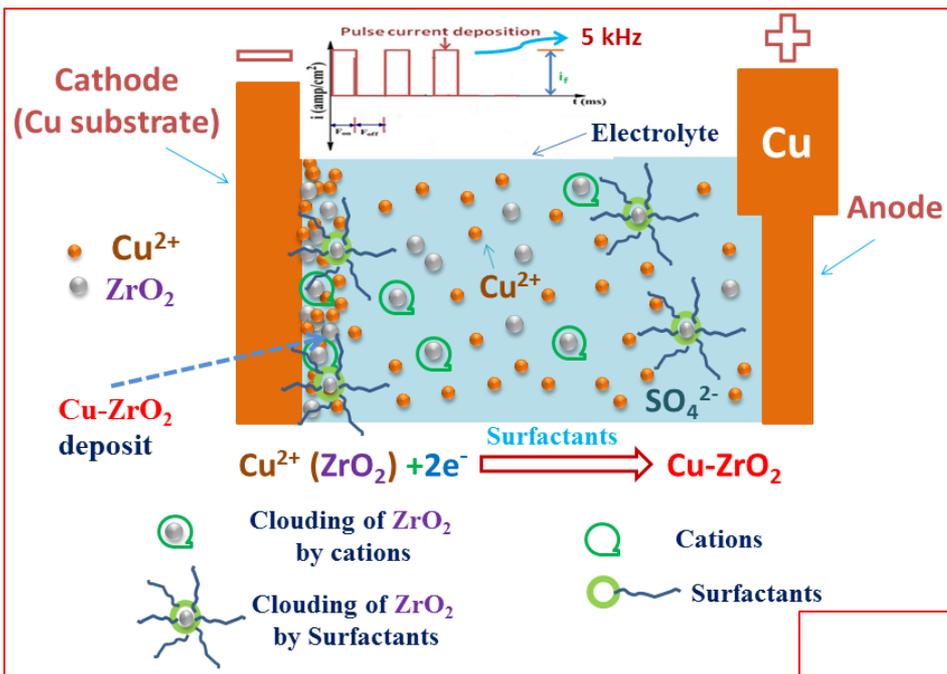
Lower electrical conductivity
(0.5 and 1g/l CTAB added coating)



- Insulating ZrO_2 codeposition
- Duplex structure

Higher surface roughness → Lower contact area → Lower electrical conductivity





Conclusions:

- ❑ After addition of CTAB in the electrolyte the developed Cu-ZrO₂ composite coating shows unique nano-cone structures.
- ❑ By considering all the properties, 0.5 g/l CTAB assisted Cu-ZrO₂ coating was considered as best among all developed coatings.
- ❑ Hardness obtained in the present study was quite high compared to earlier reported literatures. These observations are attributed towards nano-cone structure, amount of ZrO₂ added to the coating and crystallographic orientation.
- ❑ Coating obtained with CTAB shows marginal drop in electrical conductivity compared to non CTAB assisted composite specimen. The coatings obtained in the present study can be used for possible electrical applications with better surface mechanical property.

Acknowledgement:

Council of Scientific and Industrial Research, India (grant no. 22/0563/11/EMR-II).

